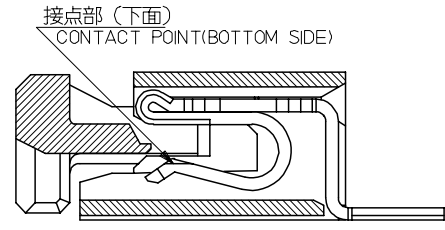
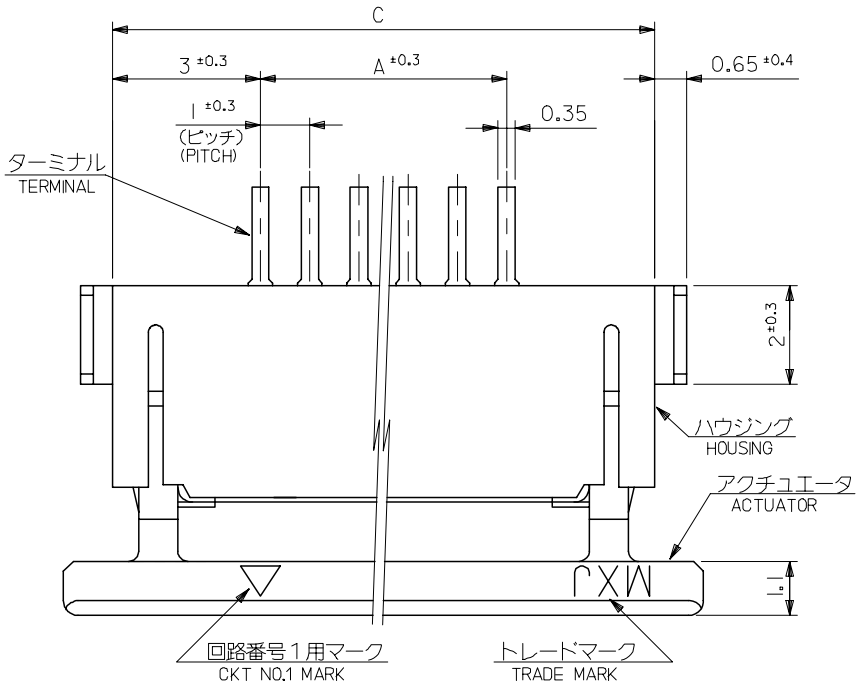
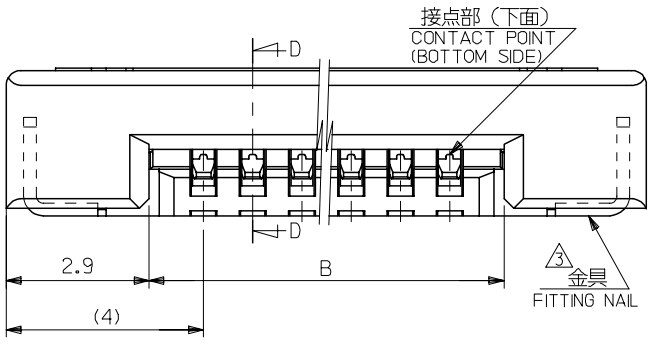
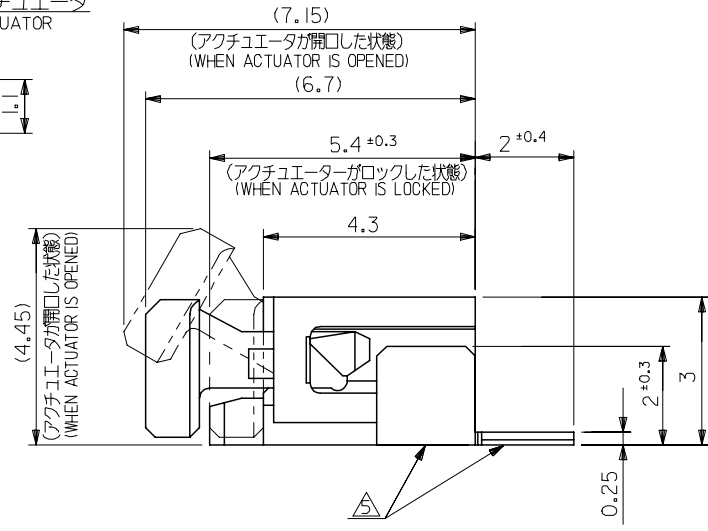


10 9 8 7 6 5 4 3 2 1

F
E
D
C
B
A



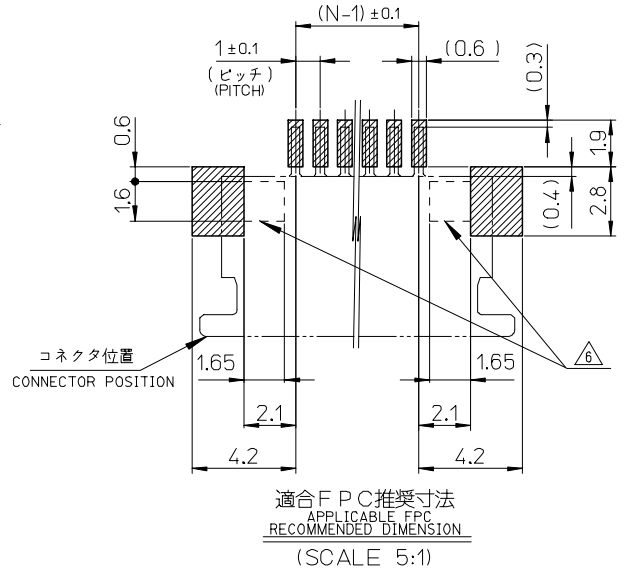
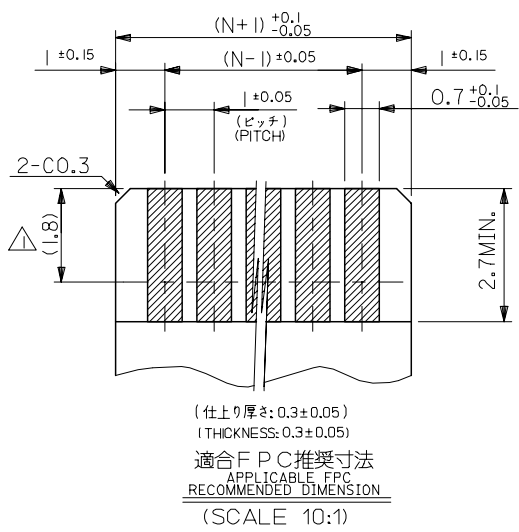
SECT. D-D



35	31.2	29	52271-3029	30
34	30.2	28	52271-2929	29
33	29.2	27	52271-2829	28
32	28.2	26	52271-2729	27
31	27.2	25	52271-2629	26
30	26.2	24	52271-2529	25
29	25.2	23	52271-2429	24
28	24.2	22	52271-2329	23
27	23.2	21	52271-2229	22
26	22.2	20	52271-2129	21
25	21.2	19	52271-2029	20
24	20.2	18	52271-1929	19
23	19.2	17	52271-1829	18
22	18.2	16	52271-1729	17
21	17.2	15	52271-1629	16
20	16.2	14	52271-1529	15
19	15.2	13	52271-1429	14
18	14.2	12	52271-1329	13
17	13.2	11	52271-1229	12
16	12.2	10	52271-1129	11
15	11.2	9	52271-1029	10
14	10.2	8	52271-0929	9
13	9.2	7	52271-0829	8
12	8.2	6	52271-0729	7
11	7.2	5	52271-0629	6
10	6.2	4	52271-0529	5
9	5.2	3	52271-0429	4
C	B	A	MATERIAL NO.	CIRCUITS

52271-**29		MODEL NO.
SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
TITLE 1.0 FPC CONN ZIF SMT (BOTTOM CONTACT) -LEAD FREE-		
MOLEX MOLEX INCORPORATED		
DOCUMENT NO. SD-52271-038		SHEET NO. 1 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

REVISED EC NO: J2006-1261 DRWN:UMEDA CHKD:KTOYODA APPR:NUKITA	DESCRIPTION 2005/10/19 2005/10/19 2005/10/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	
		10 UNDER	± 0.2	DRAWN BY M.UMEDA	DATE 2005/03/08
		10 OVER 30 UNDER	± 0.25	CHECKED BY K.TOYODA	DATE 2005/03/08
		30 OVER	± 0.3	APPROVED BY N.UKITA	DATE 2005/03/08
		ANGULAR	$\pm 3^\circ$	MATERIAL NO.	SEE CHART
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3	



注記 NOTES

- △1 接点部までの嵌合長さ。
LENGTH TO CONTACT POINT.
- 2. 使用材料 MATERIAL
 - ハウジング : 46 NYLON, UL94V-0
HOUSING
 - アクチュエータ : PPS, UL94V-0
ACTUATOR
 - ターミナル : リン青銅 (t=0.25)
TERMINAL PHOSPHOR BRONZE (t=0.25)
 - メッキ : 接点部: 金メッキ : 0.1 MICROMETER MIN.
CONTACT PORTION : GOLD PLATING : 0.1 MICROMETER MIN.
半田付部: 錫メッキ : 1.0 MICROMETER MIN.
SOLDERING PORTION : TIN PLATING : 1.0 MICROMETER MIN.
下地: ニッケルメッキ : 1.0 MICROMETER MIN.
UNDER PLATING : NICKEL PLATING : 1.0 MICROMETER MIN.
 - 金具 : 銅合金 (t=0.25)
FITTING NAIL CAPPER ALLOY (t=0.25)
 - メッキ: 錫メッキ : 1.0 MICROMETER MIN.
PLATING : TIN PLATING : 1.0 MICROMETER MIN.
下地: ニッケルメッキ : 1.0 MICROMETER MIN.
UNDER PLATING : NICKEL PLATING : 1.0 MICROMETER MIN.
- △3 パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING
OF P.C.B. PATTERN.
- 4. エンボステープ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO.54550-***29 SHOULD BE LOCKED.
- △5 テール及び金具の平坦度は、0.15以下とする。
TAIL AND NAIL COPLANARITY TO BE 0.15 MAXIMUM.
- △6 パターン書き込み禁止エリア
NO FOOT PRINT AREA.

FPCについて:

打抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は、熱硬化接着剤を推奨致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION :
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO: J2006-1261 DRW: NUKEDA CHK: KIKUYODA APP: NUKITA	DESCRIPTION 2005/10/19 2005/10/19 2005/10/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		52271-**29		MODEL NO.		
		10 UNDER	±0.2	DRAWN BY M.UMEDA	DATE 2005/03/08	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 OVER 30 UNDER	±0.25	CHECKED BY K.TOYODA	DATE 2005/03/08	TITLE 1.0 FPC CONN ZIF SMT (BOTTOM CONTACT) -LEAD FREE-				
		30 OVER	±0.3	APPROVED BY N.UKITA	DATE 2005/03/08	MOLEX INCORPORATED				
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-52271-038		SHEET NO. 2 OF 2		
SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										